TEST REPORT 01-22-2013

These tests were performed with the Coilcraft NA6111-AL transformer.

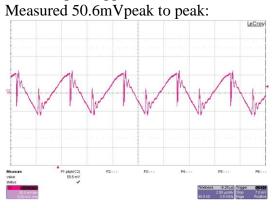
Efficiency and Regulation

				J3	J3	J3	
Iout	Vout	Iout	Vout	Iin	Vin	Eff	
2.00	3.329	1.00	5.064	0.3772	36.00	86.3%	
2.00	3.329	0.50	5.086	0.2942	36.00	86.9%	
2.00	3.329	0.00	5.108	0.2136	36.00	86.6%	
0.00	3.331	1.00	4.945	0.1573	36.00	87.3%	
0.00	3.331	0.00	4.989	0.0098	36.00	0.0%	
1.00	3.330	0.50	5.025	0.1848	36.00	87.8%	
1.00	3.330	1.00	5.003	0.2637	36.00	87.8%	
				J3	J3	J3	
<u>Iout</u>	Vout	<u>Iout</u>	Vout	<u> Iin</u>	Vin	<u>Eff</u>	
2.00	3.329	1.00	5.051	0.2754	48.00	88.6%	
2.00	3.329	0.50	5.069	0.2163	48.00	88.5%	
2.00	3.329	0.00	5.088	0.1585	48.00	87.5%	
0.00	3.331	1.00	4.951	0.1178	48.00	87.6%	
0.00	3.331	0.00	4.987	0.0094	48.00	0.0%	
1.00	3.330	0.50	5.018	0.1378	48.00	88.3%	
1.00	3.330	1.00	5.000	0.1948	48.00	89.1%	
				J3	J3	J3	
<u>Iout</u>	Vout	<u>Iout</u>	Vout	<u> Iin</u>	<u>Vin</u>	<u>Eff</u>	
2.00	3.329	1.00	5.045	0.2303	57.00	89.2%	
2.00	3.329	0.50	5.062	0.1815	57.00	88.8%	
2.00	3.329	0.00	5.079	0.1337	57.00	87.4%	
0.00	3.331	1.00	4.953	0.1001	57.00	86.8%	
0.00	3.331	0.00	4.987	0.0095	57.00	0.0%	
1.00	3.330	0.50	5.015	0.1166	57.00	87.8%	
1.00	3.330	1.00	4.999	0.1639	57.00	89.2%	
	Load Ef	<u>ficiency</u>	<u>y withou</u>	<u>ut</u>			
bridge	<u>e</u>	ı	ı	ı			
<u>Iout</u>	Vout	<u>Iout</u>	Vout	<u>Iin</u>	Vin	Eff	
2.00	3.329	1.00	5.064	0.3772	34.16	91.0%	36.0V at J3
2.00	3.329	1.00	5.051	0.2754	46.21	92.0%	48.0V at J3
2.00	3.329	1.00	5.045	0.2303	55.28	91.9%	57.0V
2.00	3.32)	1.00	3.013	0.2303	33.20	71.7/0	at J3
Vin measured at FB1/FB2							

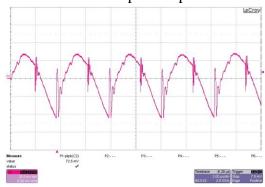
Ripple and Noise

48V input; 3.3V/2A, 5V/1A loads; 20MHz BWL.

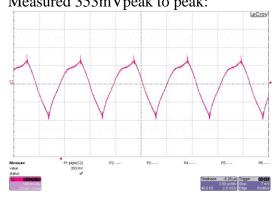
3.3V Output Ripple (C22), 20mV/div



5V Output Ripple (C14), 20mV/div Measured 72.5mV peak to peak:

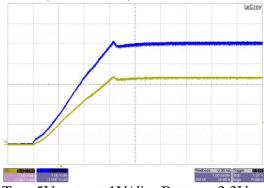


Input Ripple (C15), 100mV/div Measured 353mVpeak to peak:

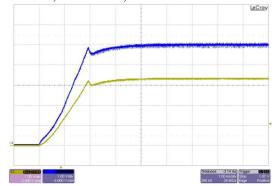


Turn On Response





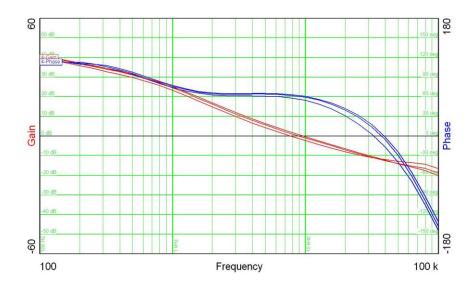
48VIN, 0A Loads, 1msec.div:



Top, 5V output, 1V/div; Bottom, 3.3V output, 1V/div

Loop Stability

The measured Bode plot of the converter is shown below.



Vin	BW	PM	GM
Volts	KHz	Deg	<u>dB</u>
36.00	7.7	58.0	11.1
48.00	8.9	60.0	12.1
57.00	9.7	60.0	12.2

Dynamic Loading

One output was pulsed. The output not being pulsed was loaded to its max value.

36V INPUT

3.3V load step, 200mA to 1A: 3.3V Response 50mV/div, 1msec/div Measured 83mV peak to peak: Measured 148mV peak to peak: Measured 148mV peak to peak:

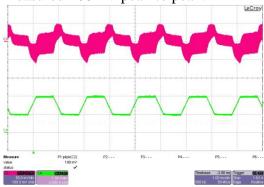
PMP8454 REV D TEXAS INSTRUMENTS

TEST REPORT 01-22-2013

3.3V load step, 1A to 2A: 3.3V Response

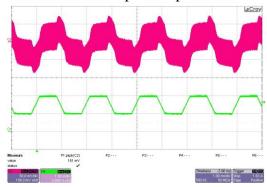
3.3V Response 50mV/div, 1msec/div

Measured 108mV peak to peak:



5V Response 50mV/div

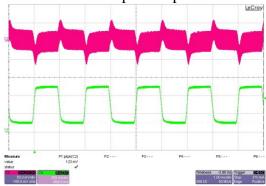
Measured 161mV peak to peak:



5V load step, 100mA to 500mA:

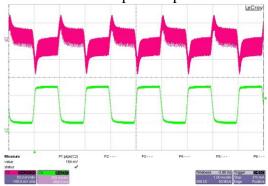
3.3V Response 50mV/div, 1msec/div

Measured 123mV peak to peak:



5V Response 50mV/div

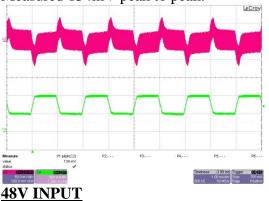
Measured 164mV peak to peak:



5V load step, 500mA to 1A:

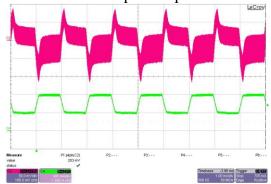
3.3V Response 50mV/div, 1msec/div

Measured 134mV peak to peak:



5V Response 50mV/div

Measured 203mV peak to peak:



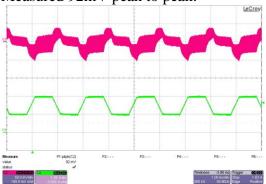
PMP8454 REV D TEXAS INSTRUMENTS

TEST REPORT 01-22-2013

3.3V load step, 1A to 2A: 3.3V Response

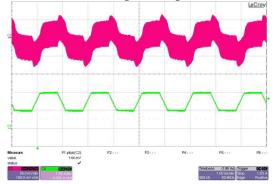
3.3V Response 50mV/div, 1msec/div

Measured 92mV peak to peak:



5V Response 50mV/div

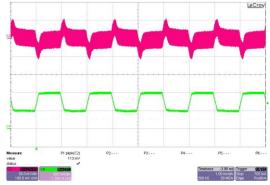
Measured 144mV peak to peak:



<u>5V load step, 500mA to 1A:</u> 3.3V Response

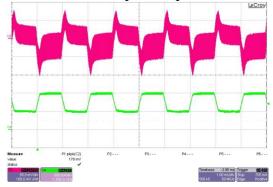
3.3V Response 50mV/div, 1msec/div

Measured 113mV peak to peak:

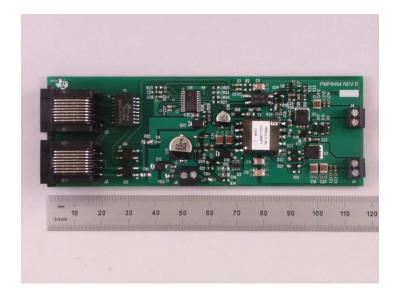


5V Response 50mV/div

Measured 178mV peak to peak:



Photo



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>